

Amendments to the Specification

Please make the following corrections in the original specification of the above-referenced application. Applicant respectfully submits that the corrections do not constitute new matter.

Please amend paragraph [2], lines 2 and 5 as follows:

With the rapid developments in semiconductor and digital technologies, electric and electronic devices, as well as intelligence devices, ~~became~~ have become much more functional and miniaturized. However, those devices often react to minute interferences caused by electromagnetic waves and thus operate poorly. Therefore, in order to ensure that the device performs optimally and ~~achieve~~ achieves product reliability, there is a need in the art for a method of conducting the electromagnetic waves, which are generated in the electric and electronic devices, outside.

Please amend paragraph [29], line 4 as follows:

Then, in the card 200 and in/ejector 300 mounted in the shelf (shown in Fig. 6), the conductive frame ground 210 formed in upper and lower parts of the card 200 is connected to an upper part of the body 120 of the guide supporter 110. The guide supporter 110 has common conductivity ~~an~~ and is formed in upper and lower parts of the shelf 100.

Amendments to the Drawings

The attached replacement sheet of drawings includes changes to Figure 1. This sheet replaces the original Figure 1. In the replacement sheet depicting the changed Figure 1, reference numeral 220 was replaced with reference numeral 200. In addition, 'A' of line A-A' was resubmitted in a more readable form.

Attachments: Replacement Sheet